

SINGULAR AND CO-MOLDED PRE-FORMS

Abstract of the Disclosure

Molded pre-forms that are used to protect electronic components and assemblies from damage due to vibration, shock and/or thermal exposure. The pre-forms can be singularly molded or co-molded. Co-molded pre-forms can include hard surface layers over softer molded compositions. The pre-forms are molded in molds that are formed using modified images obtained from printed circuit boards having the electronic components thereon. Images of the printed circuit boards are obtained and modified to improve vibrational dampening and/or heat transfer. The molded pre-forms allow for access to the printed circuit boards for purposes of replacing or repairing the printed circuit boards. The molded pre-forms are particularly suitable for down hole applications.